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JRW/B

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

MICHAEL A. LAMSON ET AL.

Serial No. 09/989,263 (TI-31189)

Filed November 19, 2001

For: LOW CAPACITANCE COUPLING WIRE  
BONDED SEMICONDUCTOR DEVICE

Art Unit 2823

Examiner Julio J. Maldonado

Customer No. 23494

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9-7-04

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CCOMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Sir:

Responsive to the statement of reasons for allowance, in addition to the reasons advanced by the Examiner as to claims 1, 3 to 7, 10 to 12, 14 and 16, claim 18 does not require the features enumerated. Rather, claim 18 relates to a plastic encapsulated semiconductor device having decreased self and mutual bond wire capacitance having a plurality of wire bonds connecting pads on an integrated circuit chip to conductive leads, a foamed polymer sheath surrounding each wire covering substantially only the wire and wire connections to the pads on the integrated circuit chip and to the conductive leads, and not covering other portions of the chip and the conductive leads with a mold compound

encasing the chip, sheathed wires, and leads. It can be seen that none of the reasons for allowance of claims 1, 3 to 7, 10 to 12, 14 and 16 are contained in claim 18.

Respectfully submitted,



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